

PMP20637 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
IPCB600	1		PMP20637	Any	Printed Circuit Board	
C600, C601	2	0.01uF	06031C103JAT2A	AVX	CAP, CERM, 0.01 µF, 100 V, +/- 5%, X7R, 0603	0603
C603, C607, C608, C611, C612	5	0.022uF	CGA6N4NP02J223J230AA	TDK	CAP, CERM, 0.022 µF, 630 V, +/- 5%, COG/NP0, AEC-Q200 Grade 0, 1210	1210
C604, C625	2	1uF	B58031I5105M002	TDK	CAP, CERM, 1 µF, 500 V, +/- 20%, B58031, AEC-Q200 Grade 0, 6.84x7.85mm	6.84x7.85mm
C605, C606	2	0.1uF	GRM43DR72J104KW01L	MuRata	CAP, CERM, 0.1uF, 630V, +/-10%, X7R, 1812	1812
C610	1	1uF	C1608X7R1E105K080AB	TDK	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0603	0603
C613	1	1000pF	GRM155R61A102KA01D	MuRata	CAP, CERM, 1000pF, 10V, +/-10%, X5R, 0402	0402
C615	1	2200pF	DE1E3KX222MA4BL01	MuRata	CAP, CERM, 2200 pF, 250 V, +/- 20%, E, Cap, 7x12x9 mm	Cap, 7x12x9 mm
C616	1	10uF	C3225X7R1E106M250AC	TDK	CAP, CERM, 10 µF, 25 V, +/- 20%, X7R, 1210	1210
C617	1	10uF	GRM21BR71A106KE51L	MuRata	CAP, CERM, 10uF, 10V, +/-10%, X7R, 0805	0805
C618, C620	2	0.1uF	C1005X7R1H104K050BB	TDK	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0402	0402
C619	1	2200pF	GRM155R71E222KA01D	MuRata	CAP, CERM, 2200pF, 25V, +10%, X7R, 0402	0402
C621	1	0.01uF	C1608X7R1H103K080AA	TDK	CAP, CERM, 0.01 µF, 50 V, +/- 10%, X7R, 0603	0603
C622	1	2.2uF	C0603C225K8PACTU	Kemet	CAP, CERM, 2.2uF, 10V, +/-10%, X5R, 0603	0603
C623	1	220pF	06031C221KAT2A	AVX	CAP, CERM, 220pF, 100V, +/-10%, X7R, 0603	0603
C624	1	0.1uF	06033C104JAT2A	AVX	CAP, CERM, 0.1uF, 25V, +/-5%, X7R, 0603	0603
D600, D601	2	30V	BAT54S-7-F	Diodes Inc.	Diode, Schottky, 30 V, 0.2 A, SOT-23	SOT-23
H600, H601, H602, H603	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H604, H605, H606, H607	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
J603	1		0448120024	Molex	Receptacle, 2.54mm, 6x1, Gold, TH	Receptacle, 2.54mm, 6x1, TH
J604	1		87758-4016	Molex	Header, 2mm, 20x2, Gold, TH	20x2 Header
J605	1		TMM-113-01-L-S-RA	Samtec	Header, 2mm, 13x1, Gold, R/A, TH	Header, 2mm, 13x1, R/A, TH
J606, J610	2		923345-02-C	3M	Jumper Wire, 200mil spacing, Red, pkg of 200	200 mil Jumper Wire
J607	1		PBC02DAAN	Sullins Connector Solutions	Header, 2.54mm, 2x2, Gold, TH	Header, 2.54mm, 2x2, TH
J608	1		PBC03DAAN	Sullins Connector Solutions	Header, 100mil, 3x2, Gold, TH	Sullins 100mil, 2x3, 230 mil above insulator
J609	1		TSW-104-07-G-D	Samtec	Header, 100mil, 4x2, Gold, TH	4x2 Header
L600	1	2.2uH	SDR0403-2R2ML	Bourns	Inductor, Drum Core, Ferrite, 2.2 µH, 2.6 A, 0.047 ohm, SMD	4.5x3.2x4mm
R600	1	0	CRCW2010000Z0EF	Vishay-Dale	RES, 0, 5%, 0.75 W, AEC-Q200 Grade 0, 2010	2010
R601	1	10.0k	ERJ-2RKF1002X	Panasonic	RES, 10.0 k, 1%, 0.1 W, 0402	0402
R602, R603	2	499k	CRCW1206499KFKEA	Vishay-Dale	RES, 499 k, 1%, 0.25 W, 1206	1206
R604	1	15.4k	CRCW060315K4FKEA	Vishay-Dale	RES, 15.4 k, 1%, 0.1 W, 0603	0603
R605, R606	2	0	RMCF0603ZT0R00	Stackpole Electronics Inc	RES, 0, 1%, 0.1 W, AEC-Q200 Grade 0, 0603	0603
R607	1	2.0k	CRCW06032K00JNEA	Vishay-Dale	RES, 2.0k ohm, 5%, 0.1W, 0603	0603
R608	1	100k	CRCW0402100KFKEA	Vishay-Dale	RES, 100k ohm, 1%, 0.063W, 0402	0402
R609	1	14.3k	CRCW060314K3FKEA	Vishay-Dale	RES, 14.3 k, 1%, 0.1 W, 0603	0603
R610	1	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00 k, 1%, 0.1 W, 0603	0603
TP600, TP601, TP602	3		0312-0-15-15-34-27-10-0	Mill-Max	Pin Receptacle, .032-.046" .075" Dia, Gold, TH	Pin Receptacle

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TP603, TP605	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP604, TP606	2		5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U600	1		LM20BIM7	Texas Instruments	2.4V, 10µA Temperature Sensor, 5-pin SC-70 Micro SMD	MAA05A
U601	1		TPS62153RGTT	Texas Instruments	Buck Step Down Regulator with 3 to 17 V Input and 5 V Output, -40 to 85 degC, 16-Pin QFN (RGT), Green (RoHS & no Sb/Br)	RGT0016C
C602	0	10uF	C1608X5R1E106M080AC	TDK	CAP, CERM, 10 µF, 25 V, +/- 20%, X5R, 0603	0603
J600	0		PEC02SAAN	Sullins Connector Solutions	Header, 100mil, 2x1, Tin, TH	Header, 2 PIN, 100mil, Tin
J601	0		PETC-02-12-02-01-L-RA-LC	Samtec	Signal Power Combo Terminal Strip, 4x3, 4 Power Group, R/A, Gold, TH	Connector, 4x3, 4 Power Group, R/A, TH
J602	0		ASP-196679-01	Samtec	Header, 2mm, 10x2, Gold, TH	Header, 2mm, 10x2, TH

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